

What is claimed is:

1. A silicon platform for optical modules comprising:
 - a silicon substrate;
 - a first insulating layer formed on the silicon substrate;
 - a first conductor layer formed on the first insulating layer;
 - a second insulating layer formed on the first conductor layer;and
 - a second conductor layer formed on the second insulating layer,
 - an end portion of the second conductor layer overlying the first insulating layer to constitute bonding portions connected to lead wires.
2. A silicon platform for optical modules according to claim 1, wherein a hole is formed in the second insulating layer and a bonding portion is formed in this hole.
3. A silicon platform for optical modules according to claim 1, wherein a removed portion is formed in the second insulating layer and a bonding portion is formed in this removed portion.
4. A silicon platform for optical modules according to claim 1, wherein the second insulating layer has a thickness of 6 μm or less.

5. A silicon platform for optical modules according to claim 1, wherein optical elements are mounted and an end portion of the second conductor layer lies right below the optical elements.

6. A silicon platform for optical modules according to claim 1, wherein a bulky portion is formed on part of the first insulating layer.

7. A silicon platform for optical modules according to claim 1, wherein the first conductor layer, the second insulating layer and the second conductor layer constitute a microstrip line structure.

8. A silicon platform for optical modules according to claim 1, wherein the second conductor layer constitutes a coplanar distribution constant circuit structure.

fc line

9. A silicon platform for optical modules according to claim 1, which is electrically connected to a driver IC by lead wires.

10. A silicon platform for optical modules according to claim 1, wherein at least one of a light emitting element and a light-receiving element are mounted.

11. A silicon platform for optical modules according to claim 1,

wherein the first insulating layer is an oxide layer.

12. A silicon platform for optical modules according to claim 1, wherein the first insulating layer is an SiO₂ insulating layer.

13. A silicon platform for optical modules according to claim 1, wherein the second insulating layer is a resin layer.

14. A silicon platform for optical modules according to claim 1, wherein the second insulating layer is a polyimide layer.